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Silicon P-Channel MOS FET

RENESAS

ADE-208-1193 (Z) 1st. Edition Mar. 2001

Application

Low frequency power amplifier

Complementary pair with 2SK2220, 2SK2221

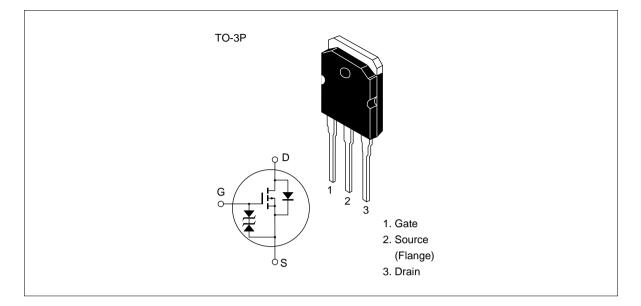
Features

- High power gain
- Excellent frequency response
- High speed switching
- Wide area of safe operation
- Enhancement-mode
- Good complementary characteristics
- Equipped with gate protection diodes

Ordering Information

Type No.	V _{DSX}
2SJ351	–180 V
2SJ352	–200 V

Outline



Absolute Maximum Ratings (Ta = 25°C)

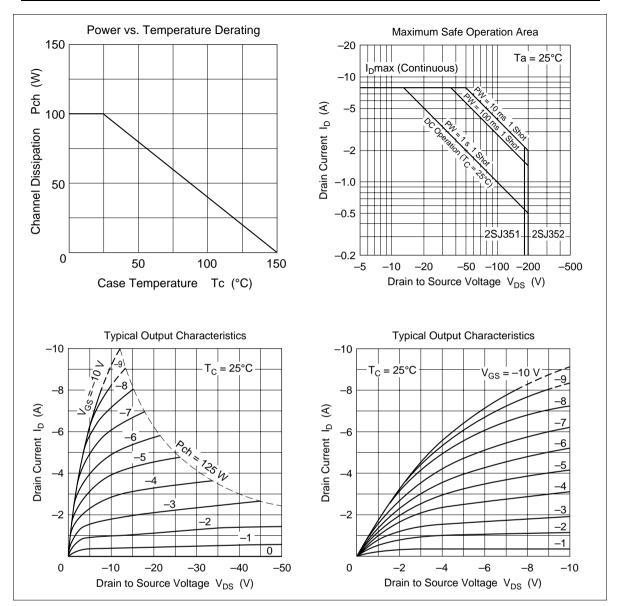
Item		Symbol	Ratings	Unit
Drain to source voltage	2SJ351	V _{DSX}	-180	V
	2SJ352		-200	
Gate to source voltage		V _{GSS}	±20	V
Drain current		I _D	-8	А
Body to drain diode reverse	e drain current	I _{DR}	-8	А
Channel dissipation		Pch*1	100	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C
Note: 1 Value at $T = 2i$	E°C			

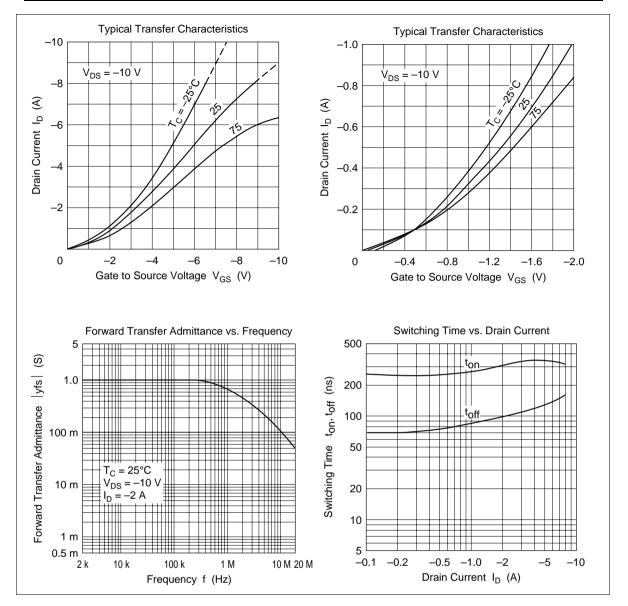
Note: 1. Value at $T_c = 25^{\circ}C$

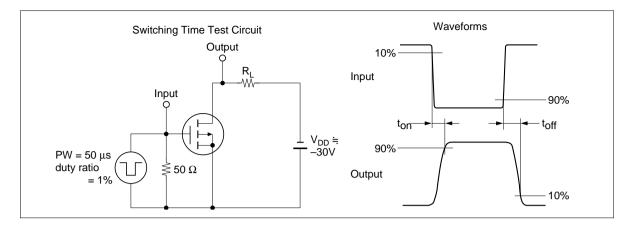
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SJ351	$V_{(BR)DSX}$	-180	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 10$ V
breakdown voltage	2SJ352		-200	_	_		
Gate to source break voltage	kdown	$V_{(\text{BR})\text{GSS}}$	±20	—	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source cutof	f voltage	$V_{GS(off)}$	-0.15	_	-1.45	V	$I_{\rm D} = -100 \text{ mA}, V_{\rm DS} = -10 \text{ V}$
Drain to source satu voltage	ration	$V_{\text{DS(sat)}}$	—	—	-12	V	$I_{\rm D} = -8$ A, $V_{\rm GD} = 0^{*1}$
Forward transfer adr	mittance	y _{fs}	0.7	1.0	1.4	S	$I_{\rm D} = -3$ A, $V_{\rm DS} = -10$ V ^{*1}
Input capacitance		Ciss	—	800	_	pF	$V_{GS} = 5 \text{ V}, V_{DS} = -10 \text{ V},$
Output capacitance		Coss	—	1000	_	pF	f = 1 MHz
Reverse transfer cap	pacitance	Crss	—	18		pF	
Turn-on time		t _{on}	_	320	_	ns	$V_{DD} = -30 \text{ V}, \text{ I}_{D} = -4 \text{ A}$
Turn-off time		t _{off}	_	120	_	ns	
Nata: A Dulas ta							

Electrical Characteristics (Ta = 25° C)

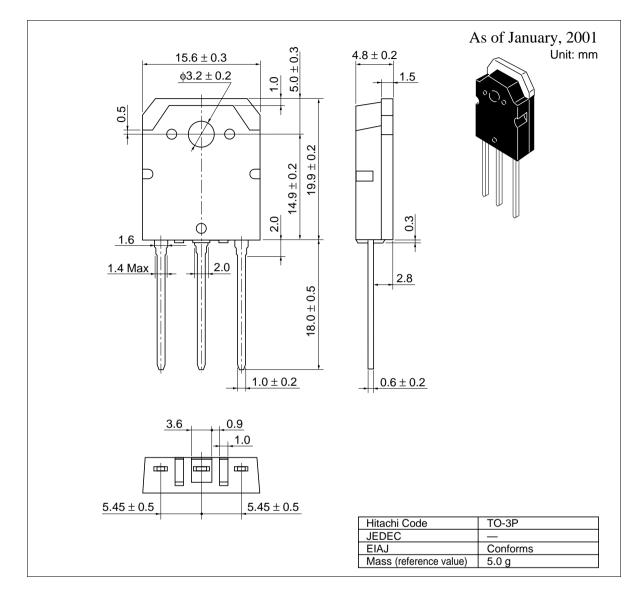
Note: 1. Pulse test







Package Dimensions



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Hitachi, Ltd.

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223		Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg	Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong
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